

IN THE CLAIMS:

4/14/05
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Please CANCEL claims 1-40 without prejudice to or disclaimer of the recited subject matter.

Please ADD new claims 41-52, as follows. For the Examiner's convenience, all claims currently pending in this application have been reproduced below:

1-40. (Cancelled)

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41. (New) A scanning exposure apparatus for exposing a substrate to a pattern, said apparatus comprising:

an exposure system which exposes the substrate to the pattern with respect to a unit region, to which the pattern is transferred, of the substrate;

a determination system which determines whether a condition of an exposure performed by said exposure system is allowable during the exposure; and

a control system which causes said exposure system to continue exposing a remaining region in the unit region of the substrate to the pattern, even after said determination system makes a negative determination for the unit region.

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42. (New) An apparatus according to claim 43, wherein the condition of the exposure includes a position of a region of the substrate.

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~~43.~~ (New) An apparatus according to claim ~~42~~, wherein the position is a position in a direction along which the pattern is projected.

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~~44.~~ (New) An apparatus according to claim ~~41~~, wherein the condition of the exposure includes a precision of an exposure control performed by said exposure system.

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~~45.~~ (New) An apparatus according to claim ~~44~~, wherein the precision of the exposure control includes at least one of an alignment sync control precision and an exposure amount control precision.

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~~46.~~ (New) A device manufacturing method comprising:

a step of exposing a substrate to a pattern using an exposure apparatus defined in

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claim ~~41~~.

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~~47.~~ (New) A scanning exposure apparatus for exposing a substrate to a pattern, said apparatus comprising:

an exposure system which exposes the substrate to the pattern with respect to a unit region, to which the pattern is transferred, of the substrate;

a determination system which determines whether a condition of an exposure performed by said exposure system is allowable during the exposure;

a control system which causes said exposure system to expose a complete region in the unit region of the substrate to the pattern, even if said determination system makes a negative determination for the unit region; and

a display system which discriminately displays the unit region, for which said determination system makes the negative determination, of the substrate.

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48. (New) An apparatus according to claim 47, wherein the condition of the exposure includes a position of a region of the substrate.

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49. (New) An apparatus according to claim 48, wherein the position is a position in a direction along which the pattern is projected.

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50. (New) An apparatus according to claim 49, wherein the condition of the exposure includes a precision of an exposure control performed by said exposure system.

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51. (New) An apparatus according to claim 50, wherein the precision of the exposure control includes at least one of an alignment sync control precision and an exposure amount control precision.

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52. (New) A device manufacturing method comprising:
a step of exposing a substrate to a pattern using an exposure apparatus defined in claim 47.